

New Patent Claims

1. A method for making contact between at least one  
module for wire-free radio standards and at least  
5 one application, with
  - contact surfaces being provided on a side of the  
module which is intended to make contact with  
the application, and
  - 10 - contact surfaces which can interact with the  
contact surfaces of the module being provided on  
a side of the application which is intended to  
make contact with the module, with
  - the contact surfaces being formed by a metallic  
15 coating with a low electrical and/or thermal  
resistance and a connection being produced  
between the respective contact surfaces of the  
module and the application.
2. The method as claimed in claim 1,  
20 characterized  
in that a detachable connection is provided  
between the respective contact surfaces by means  
of a mechanical apparatus which allows the module  
to be replaced by pushing it in and out.
- 25 3. The method as claimed in claim 1,  
characterized  
in that a firm connection is provided between the  
respective contact surfaces.
- 30 4. The method as claimed in claim 3,  
characterized  
in that the respective contact surfaces are  
soldered or pressed together.

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5. The method as claimed in one of the preceding claims, characterized in that the respective contact surfaces are arranged in the form of a grid.
6. A combination, having a module for wire-free radio standards and having an application, with the module having contact surfaces on a side which is intended to make contact with the application, and the application having contact surfaces on a side which is intended to make contact with the module, which latter contact surfaces can interact with the contact surfaces of the module and can make contact with them, with the contact surfaces being formed by a metallic coating with a low electrical and/or thermal resistance.
7. The combination as claimed in claim 6, characterized in that the respective contact surfaces can be detachably connected to one another.
8. The combination as claimed in claim 6, characterized in that the respective contact surfaces can be permanently connected to one another.
9. The combination as claimed in claim 8, characterized in that the respective contact surfaces can be soldered to one another.
10. The combination as claimed in one of claims 6 to 9,

ART 24 AND 1

